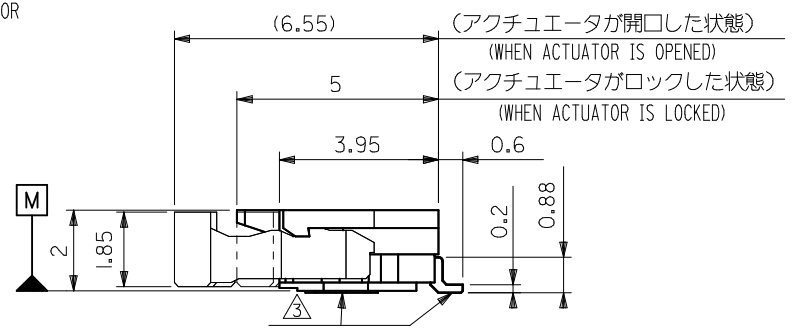
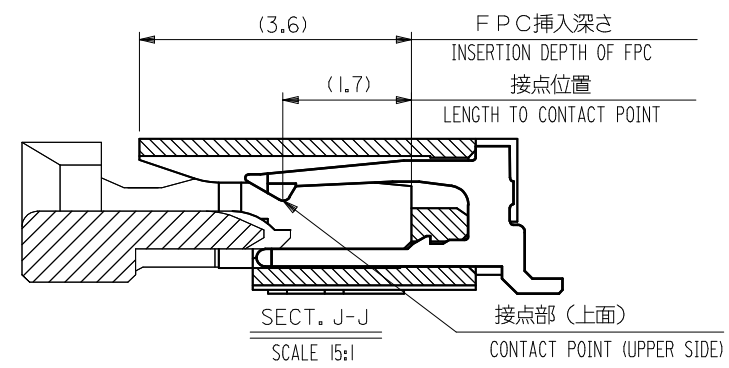
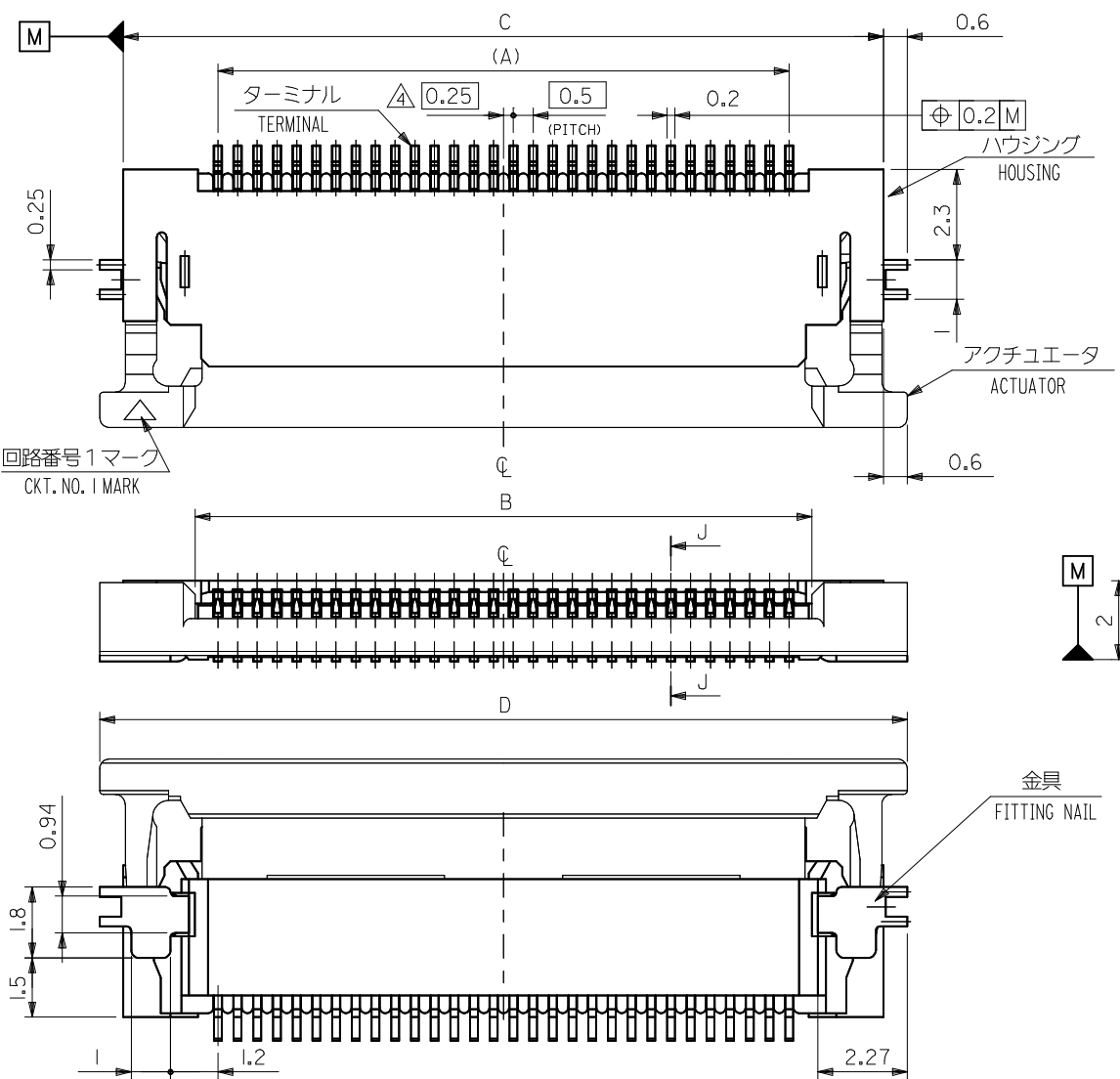


10 9 8 7 6 5 4 3 2 1

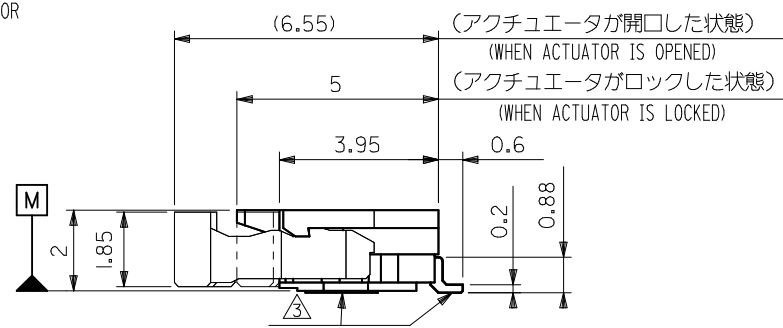
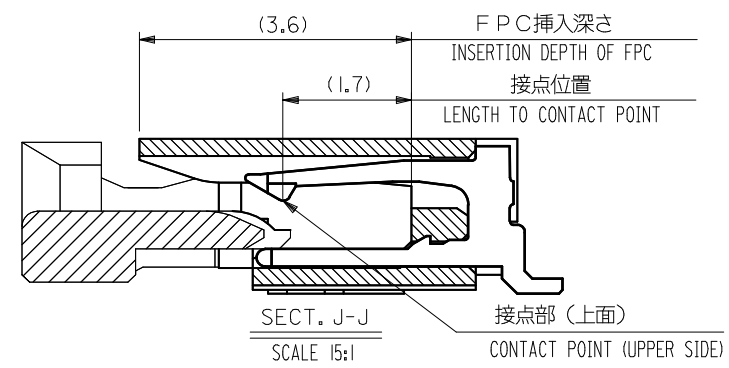
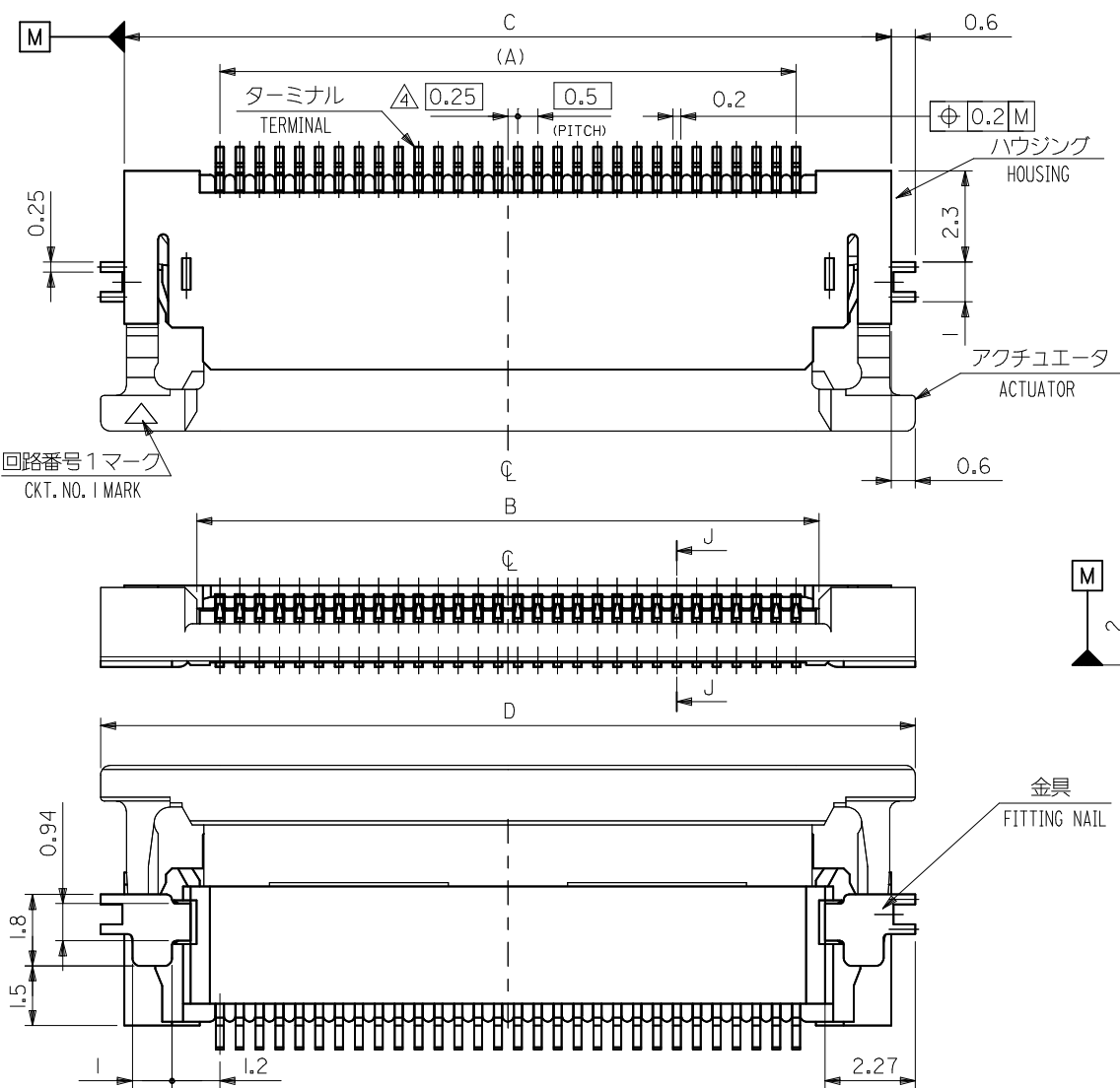


D	C	B	A	MATERIAL NO.	CKT.
30.5	29.3	25.65	24.5	54104 - 5037	50
28.5	27.3	23.65	22.5	54104 - 4637	46
28.0	26.8	23.15	22.0	54104 - 4537	45
27.0	25.8	22.15	21.0	54104 - 4337	43
23.5	22.3	18.65	17.5	54104 - 3637	36
22.5	21.3	17.65	16.5	54104 - 3437	34
21.5	20.3	16.65	15.5	54104 - 3237	32
20.5	19.3	15.65	14.5	54104 - 3037	30

REVISED EC NO: J2016-0402 DRWN: JASUNUMA 2015/10/20 CHKD: TAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED) 0.25 UNDER UNDER ±0.2 0.25 OVER 0.5 UNDER ±0.2 0.5 OVER 1.0 UNDER ±0.2 1.0 OVER 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±3 °		DIMENSION STYLE MM ONLY DRAWN BY DATE N. YANO 2000/12/13 CHECKED BY DATE S. KUNISHI 2000/12/13 APPROVED BY DATE		SCALE --- DESIGN UNITS METRIC THIRD ANGLE PROJECTION	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART DOCUMENT NO. SD-54104-023 SHEET NO. 1 OF 2		TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT molex	
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
	SIZE A3					

9 8 7 6 5 4 3 2 1

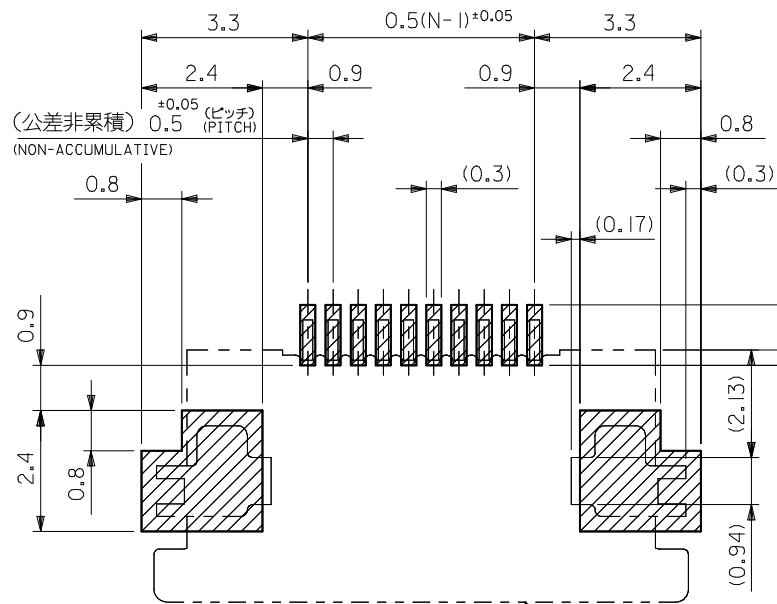
10 9 8 7 6 5 4 3 2 1



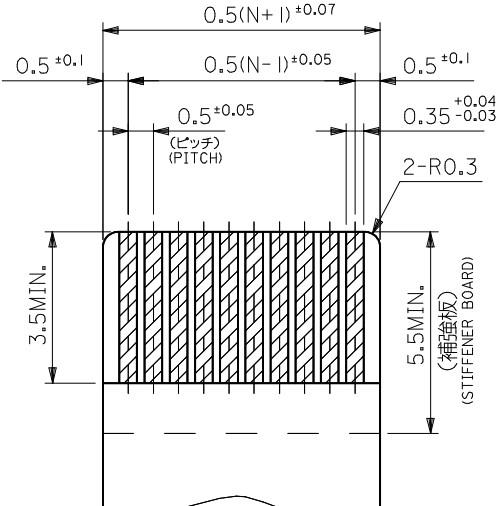
D	C	B	A	MATERIAL NO.	CKT.
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28.5	27.3	23.65	22.5	54104 - 4637	46
28.0	26.8	23.15	22.0	54104 - 4537	45
27.0	25.8	22.15	21.0	54104 - 4337	43
23.5	22.3	18.65	17.5	54104 - 3637	36
22.5	21.3	17.65	16.5	54104 - 3437	34
21.5	20.3	16.65	15.5	54104 - 3237	32
20.5	19.3	15.65	14.5	54104 - 3037	30

REVISED EC NO: J2016-0402 DRWN: JASUNUMA 2015/10/20 CHKD: TAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.2	DRAWN BY	DATE	TITLE				
	0.25 OVER	0.5 UNDER	±0.2	N. YANO	2000/12/13	0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT molex				
	0.5 OVER	1.0 UNDER	±0.2	CHECKED BY	DATE					
1.0 OVER	10 UNDER	±0.2	S. KUNISHI	2000/12/13	SD-54104-023					
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE						
30 OVER		±0.3	MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
ANGULAR ±3 °			SEE CHART		SD-54104-023		1 OF 2			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

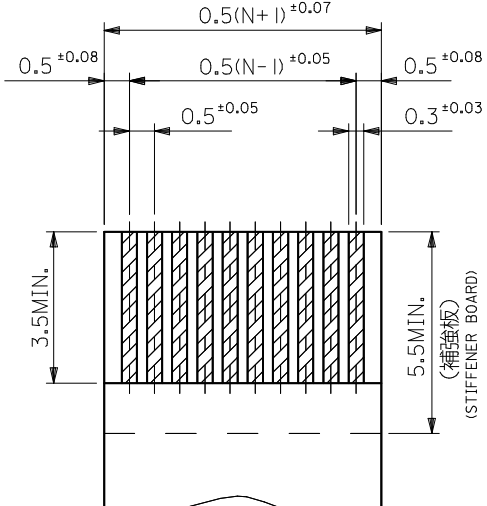
9 8 7 6 5 4 3 2 1



参考基板レイアウト
RECOMMENDED P.C. BOARD
PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

注記 NOTES

I. 使用材料 MATERIAL

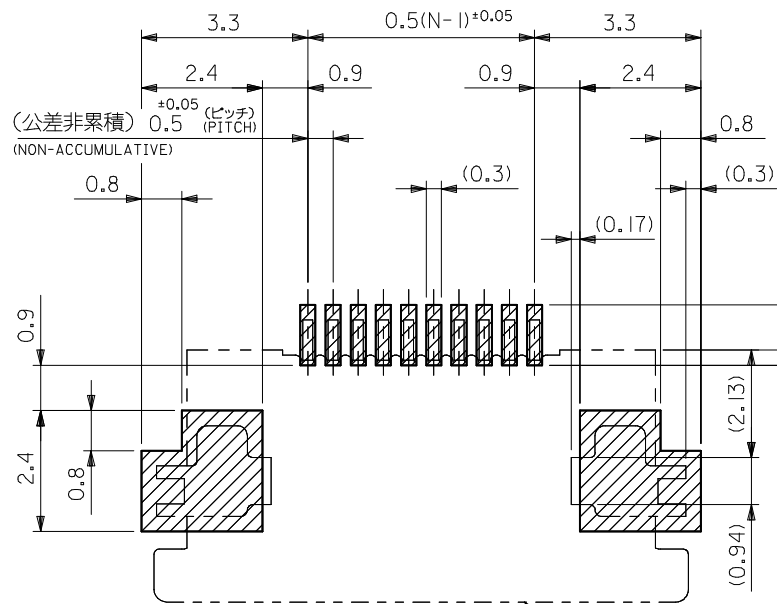
- ハウジング : 46ナイロン, UL94V-0
HOUSING 46NYLON
- アクチュエータ : PPS, UL94V-0
ACTUATOR
- ターミナル : リン青銅, 銅下地半田メッキ (t=0.2)
TERMINAL PHOS-BRO.TIN-LEAD(9:1) 3~5 MICRON METER OVER COPPER 1~2.5 MICRON METER PLATED
- 金具 : リン青銅, 銅下地半田メッキ (t=0.2)
FITTING NAIL PHOS-BRO.TIN-LEAD(9:1) 3~5 MICRON METER OVER COPPER 1~2.5 MICRON METER PLATED

- 2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54104-***37 SHOULD BE LOCKED.
- △ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX. 下方向 0.15 MAX. とし、相互のバラツキ量は、0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0.1 MAX. , LOWER DIRECTION: 0.15 MAX. OFFSET BETWEEN UPPER AND LOWER 0.1 MAX. H
- △偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

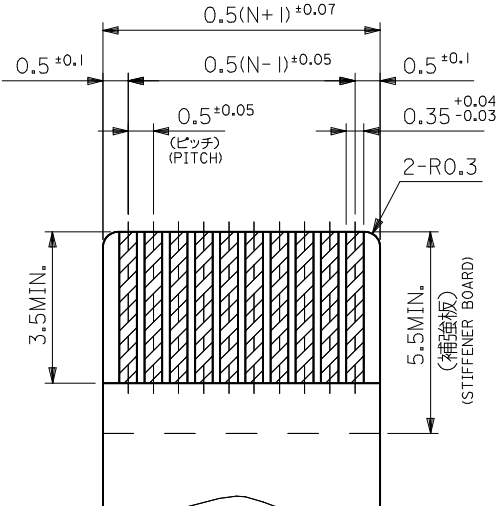
FPC/FFCについて

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルメッキ厚 3~9マイクロメートルまたは半田メッキ (電気メッキ)
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL:
35 micrometer or 50 micrometer
TIN OR SOLDER PLATING:
3~9 micrometer (ELECTRICAL PLATING)

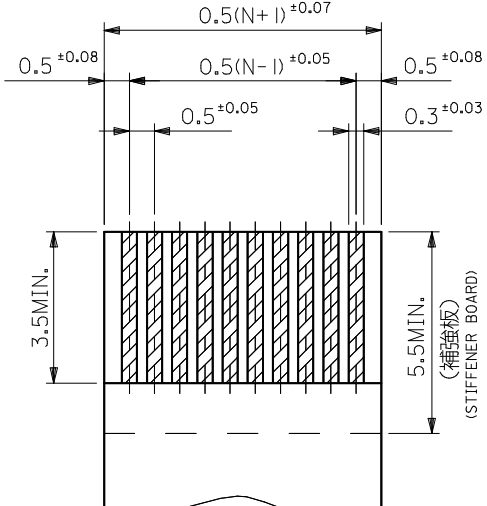
SEE SHEET 1 EC NO: J2016-0402 DRWN: JASUNUMA 2015/10/20 CHKD: TAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.2	DRAWN BY N. YANO	DATE 2000/12/13	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT	
	0.25 OVER	0.5 UNDER	±0.2	CHECKED BY S. KUNISHI	DATE 2000/12/13		
	0.5 OVER	1.0 UNDER	±0.2	APPROVED BY	DATE		
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-54104-023	SHEET NO. 2 OF 2
10 OVER	30 UNDER	±0.25	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
30 OVER		±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



参考基板レイアウト
RECOMMENDED P.C. BOARD
PATTERN DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)



適用FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)



適用FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS: 0.3±0.03)

注記 NOTES

I. 使用材料 MATERIAL

- ハウジング : 46ナイロン, UL94V-0
HOUSING 46NYLON
- アクチュエータ : PPS, UL94V-0
ACTUATOR
- ターミナル : リン青銅, 銅下地半田メッキ (t=0.2)
TERMINAL PHOS-BRO.TIN-LEAD(9:1) 3~5 MICRON METER OVER COPPER 1~2.5 MICRON METER PLATED
- 金具 : リン青銅, 銅下地半田メッキ (t=0.2)
FITTING NAIL PHOS-BRO.TIN-LEAD(9:1) 3~5 MICRON METER OVER COPPER 1~2.5 MICRON METER PLATED

- 2. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54104-***37 SHOULD BE LOCKED.
- △ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、基準面 H に対し上方向 0.1 MAX. 下方向 0.15 MAX. とし、相互のバラツキ量は、0.1 MAX. とする。
MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM UPPER DIRECTION: 0.1 MAX. , LOWER DIRECTION: 0.15 MAX. OFFSET BETWEEN UPPER AND LOWER 0.1 MAX.
- △偶数極に適用。
APPLY FOR EVEN CIRCUIT.
- △パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

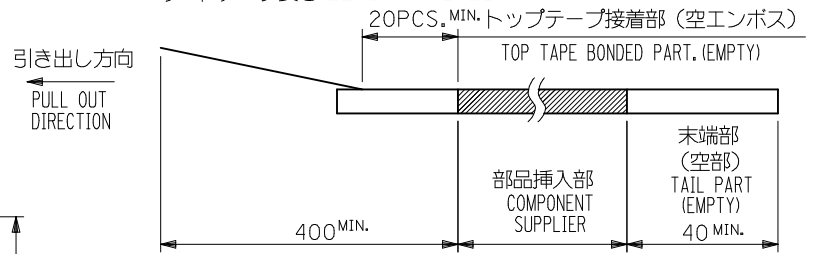
FPC/FFCについて

打抜き方向は導体側から補強板側を推奨いたします。
導体部については軟銅箔35マイクロメートルまたは50マイクロメートルメッキ厚 3~9マイクロメートルまたは半田メッキ (電気メッキ)
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED CONDUCTOR SPEC.:
THICKNESS OF SOFT COPPER FOIL:
35 micrometer or 50 micrometer
TIN OR SOLDER PLATING:
3~9 micrometer (ELECTRICAL PLATING)

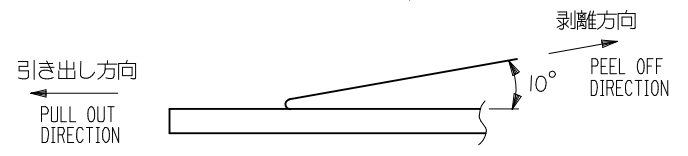
SEE SHEET 1 EC NO: J2016-0402 DRWN: JASUNUMA 2015/10/20 CHKD: TAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	0.25 UNDER	UNDER	±0.2	DRAWN BY N. YANO	DATE 2000/12/13	TITLE 0.5 FPC CONN ZIF HSG ASSY FOR SMT RA UPR CONT		
	0.25 OVER	0.5 UNDER	±0.2	CHECKED BY S. KUNISHI	DATE 2000/12/13			
	0.5 OVER	1.0 UNDER	±0.2	APPROVED BY	DATE			
	1.0 OVER	10 UNDER	±0.2	MATERIAL NO. SEE SHEET 1		DOCUMENT NO. SD-54104-023	SHEET NO. 2 OF 2	
10 OVER	30 UNDER	±0.25	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					
30 OVER		±0.3						
ANGULAR		±3 °						
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							SIZE A3	

NOTES

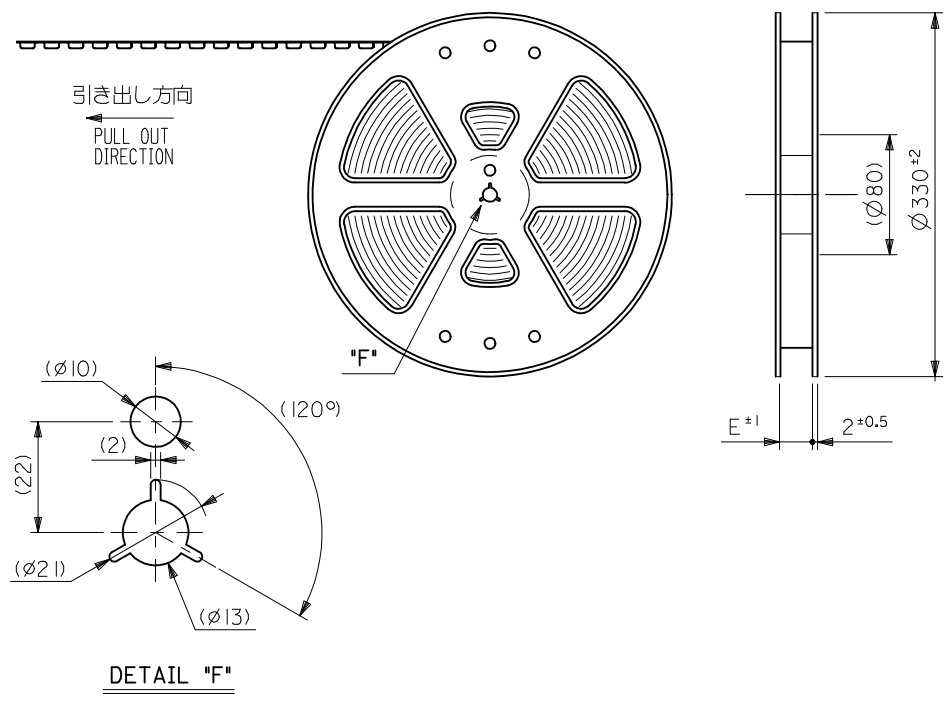
1. 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG,)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



4. 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

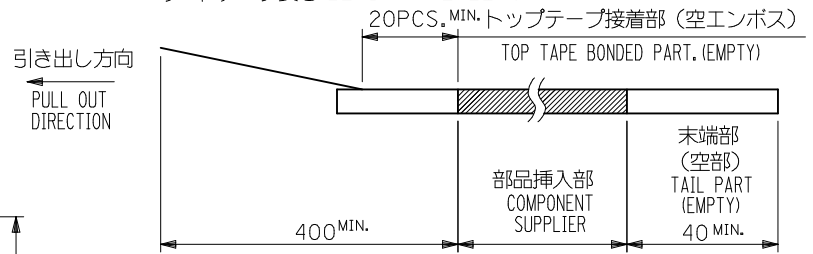


DETAIL "F"

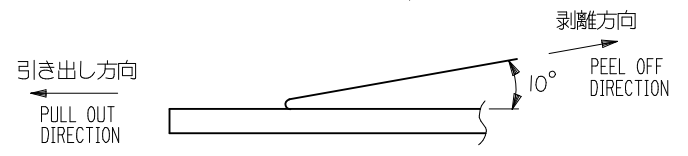
REVISED EC NO: J2016-0402 DRWN: JASUNUMA 2015/10/20 CHKD: TAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	± 0.2	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	± 0.2	NKONDO	2014/06/16	EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY		
	0.5 OVER	1.0 UNDER	± 0.2	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	± 0.2	KTAKAHASHI	2014/06/16	molex		
10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE				
30 OVER		± 0.3	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
ANGULAR	± 3 °		SEE SHEET 2		SD-54104-024		1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

NOTES

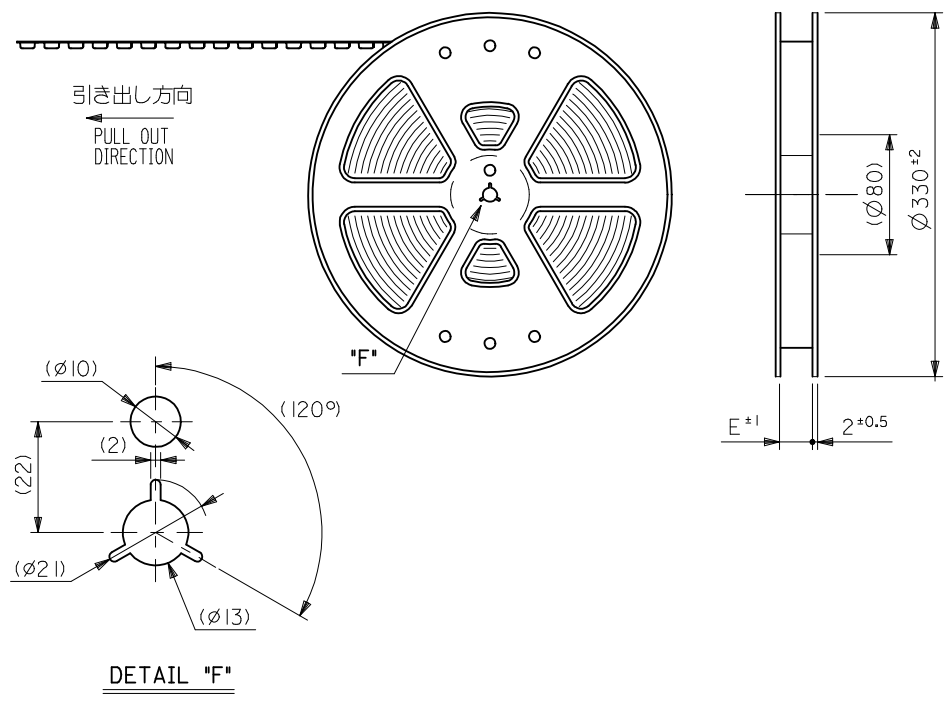
1. 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
2. リードテープ長さ LEAD TAPE LENGTH



3. トップテープの剥離強度：0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG,)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.

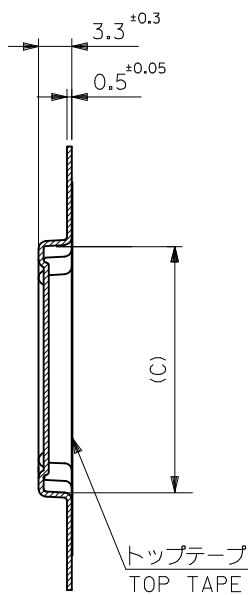


4. 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE) : ポリプロピレン (POLYPROPYLENE)
トップテープ (TOPTAPE) : PET , PE , PEF
リール (REEL) : ポリスチレン (PS) <リサイクル材を含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

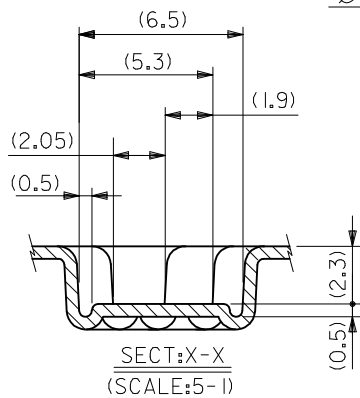
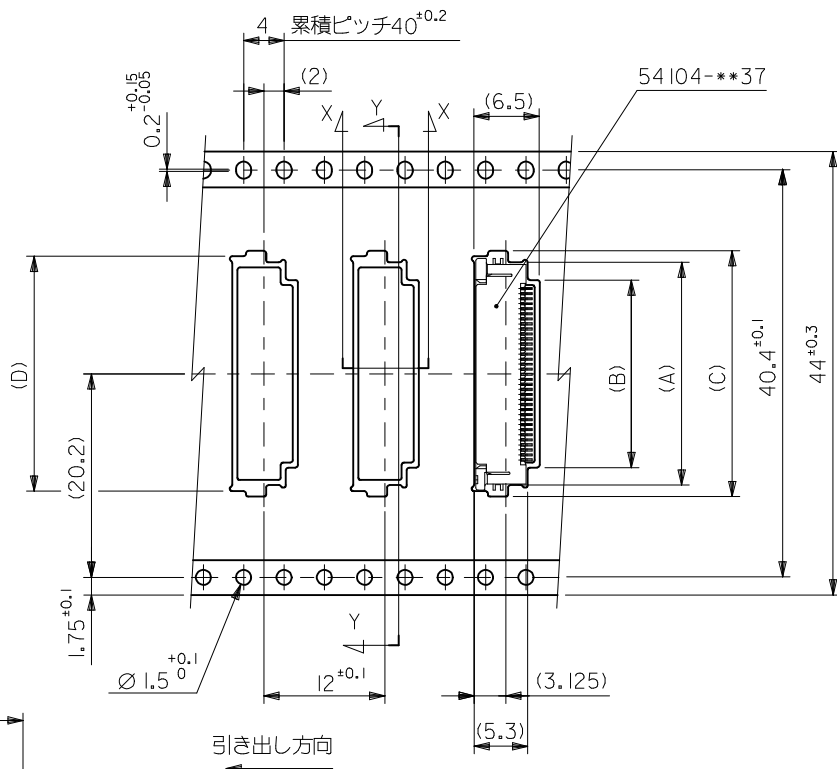


DETAIL "F"

REVISED EC NO: J2016-0402 DRWN: JASUNUMA 2015/10/20 CHKD: TAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	± 0.2	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	± 0.2	NKONDO	2014/06/16	EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY		
	0.5 OVER	1.0 UNDER	± 0.2	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	± 0.2	KTAKAHASHI	2014/06/16	molex		
10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE				
30 OVER		± 0.3	MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
ANGULAR	± 3 °		SEE SHEET 2		SD-54104-024		1 OF 2	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

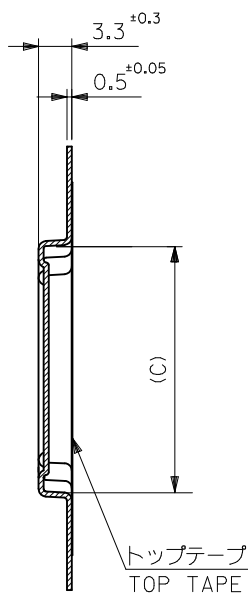


SECT:Y-Y

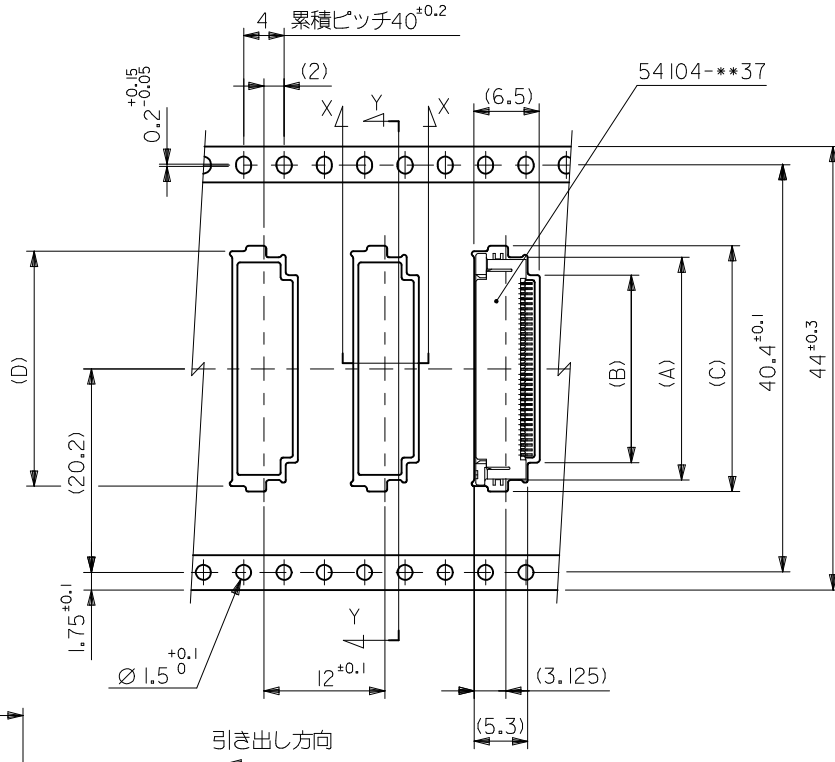
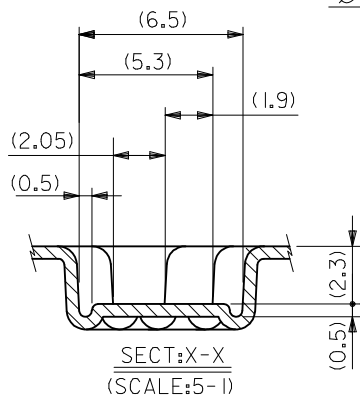


44	45.5	30.8	31.9	26.1	29.6	54104-5092	50
		28.8	29.9	24.1	27.6	-4692	46
		28.3	29.4	23.6	27.1	-4592	45
		27.3	28.4	22.6	26.1	-4392	43
		23.8	24.9	19.1	22.6	-3692	36
		22.8	23.9	18.1	21.6	-3492	34
		21.8	22.9	17.1	20.6	-3292	32
		20.8	21.9	16.1	19.6	54104-3092	30
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	C	B	A	MATERIAL NO.	CKT.

SEE SHEET 1 EC NO.: J2016-0402 DRWN: JASANUMA 2015/10/20 CHKD: KTAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY molex SD-54104-024 SHEET NO. 2 OF 2
	0.25 UNDER UNDER ±0.2			MM ONLY		---	METRIC	
	0.25 OVER 0.5 UNDER ±0.2			DRAWN BY DATE		TITLE		
	0.5 OVER 1.0 UNDER ±0.2			NKONDO 2014/06/16		EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY		
	1.0 OVER 10 UNDER ±0.2			CHECKED BY DATE		MATERIAL NO. DOCUMENT NO.		
10 OVER 30 UNDER ±0.25			KTAKAHASHI 2014/06/16		SEE CHART SD-54104-024			
30 OVER ±0.3			APPROVED BY DATE		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3			



SECT:Y-Y



44	45.5	30.8	31.9	26.1	29.6	54104-5092	50
		28.8	29.9	24.1	27.6	-4692	46
		28.3	29.4	23.6	27.1	-4592	45
		27.3	28.4	22.6	26.1	-4392	43
		23.8	24.9	19.1	22.6	-3692	36
		22.8	23.9	18.1	21.6	-3492	34
		21.8	22.9	17.1	20.6	-3292	32
		20.8	21.9	16.1	19.6	54104-3092	30
キャリアテープ幅 CARRIER TAPE WIDTH	E	D	C	B	A	MATERIAL NO.	CKT.

SEE SHEET 1 EC NO.: J2016-0402 DRWN: JASUNUMA 2015/10/20 CHKD: TAKAHASHI 2015/11/05 APPR: YNOGAWA 2015/11/16	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION EMBSTP PKG FOR 0.5 FPC CONN ZIF HSG ASSY molex SD-54104-024 SHEET NO. 2 OF 2
				MM ONLY		---	METRIC	
	0.25 UNDER	UNDER	±0.2	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.2	NKONDO	2014/06/16			
	0.5 OVER	1.0 UNDER	±0.2	CHECKED BY	DATE			
1.0 OVER	10 UNDER	±0.2	KTAKAHASHI	2014/06/16				
10 OVER	30 UNDER	±0.25	APPROVED BY	DATE				
30 OVER		±0.3	MATERIAL NO.		DOCUMENT NO.			
ANGULAR	±3 °		SEE CHART					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
			A3					